

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-197006

(43)Date of publication of application : 31.07.1997

(51)Int.Cl.

G01R 31/26

H01L 21/66

(21)Application number : 08-113884

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(22)Date of filing : 08.05.1996

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(30)Priority

Priority number : 95 580687

Priority date : 29.12.1995

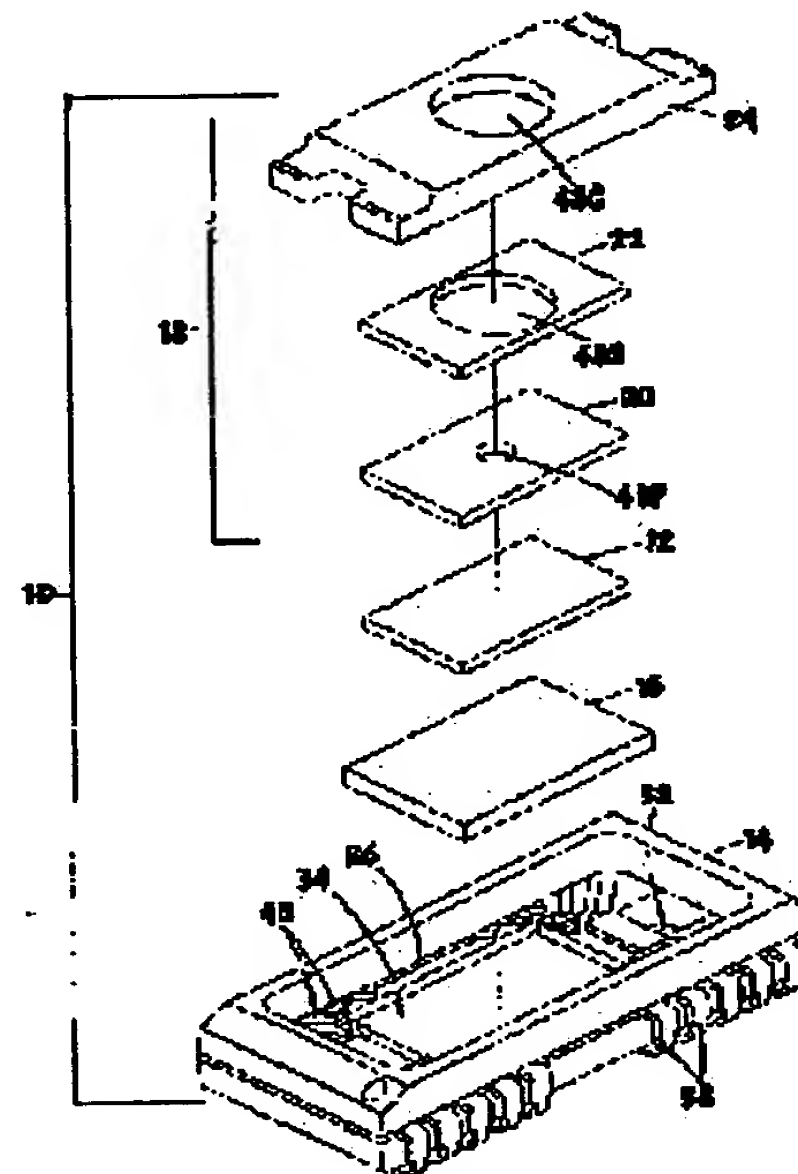
Priority country : US

## (54) METHOD AND APPARATUS FOR PACKAGING AND TESTING SEMICONDUCTOR DIE

(57)Abstract:

PROBLEM TO BE SOLVED: To make it possible to use a standard burn-in board and automated package handling apparatus by forming a temporary package for a semiconductor die having a standard profile and external lead shape, and testing the die by using the package and standard testing unit.

SOLUTION: A temporary package 10 holds a semiconductor die 12 and forms a temporary electric connection to a die 12 for testing and burning-in. After the test was finished, the die 12 is removed from the package 10, and used as the test acceptance die. That is, the package 10 has a package base 14, interconnect 16, and a pressurizing mechanism 18. The interconnect 16 electrically connects the base 14 with the die 12. The package 10 is assembled as a small outline package having a J bend lead 38, and can be burned-in by using a standard burn-in unit for normal small outline J bend package.



## LEGAL STATUS

[Date of request for examination]

09.05.1996

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

3072591

[Date of registration]

02.06.2000